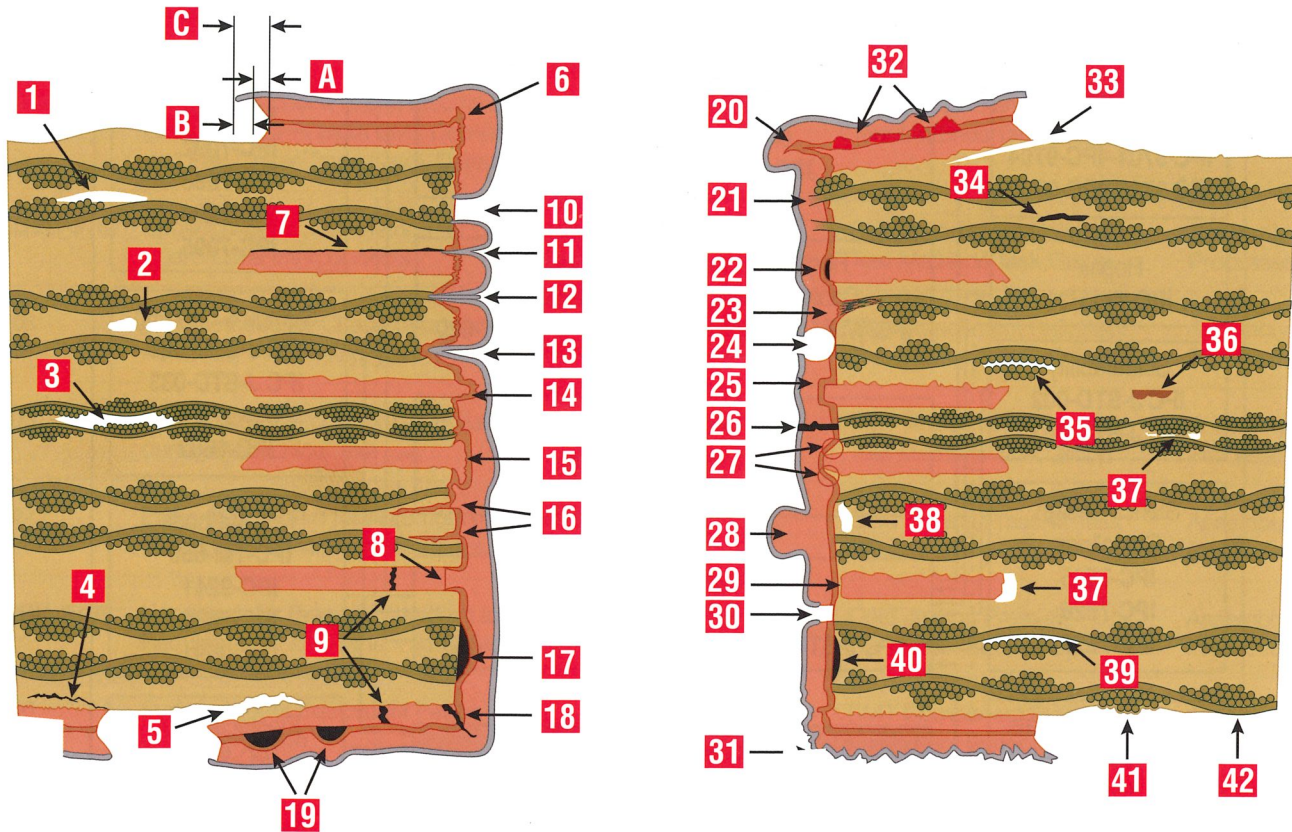


Phenomena in Cross Section of Plated Through Holes



- | | |
|--|---------------------------------|
| A Undercut | 20 Burr Pushed Into Hole |
| B Outgrowth | 21 Glass Fiber Protrusion |
| C Overhang | 22 Innerlayer (Post) Separation |
| 1 (Resin) Blistering | 23 Wicking |
| 2 Laminate Void | 24 Over Plating Resist Void |
| 3 (Resin) Delamination | 25 (Positive) Etchback |
| 4 Pad Cratering | 26 Barrel Crack |
| 5 Lifted Land Crack | 27 Shadowing |
| 6 Burr | 28 Nodule |
| 7 Bond Enhancement removed — "Pink Ring" | 29 Resin Smear |
| 8 Negative Etchback | 30 Copper & Over Plate Void |
| 9 Foil Crack | 31 Burned Plating |
| 10 Hole Plating Void | 32 Copper Foil Contamination |
| 11 Wedge Void | 33 Lifted Land |
| 12 Glass Fiber Void | 34 Resin Crack Delamination |
| 13 Glass Bundle Void | 35 Crazeing |
| 14 Severe Etchback | 36 Foreign Inclusion |
| 15 Nail Heading | 37 Prepreg Void |
| 16 Drill Wall Tear/Wicking | 38 Copper Clad Laminate Void |
| 17 Hole Wall Pull Away | 39 Measling |
| 18 Corner Crack | 40 Resin Recession |
| 19 (Copper) Blistering | 41 Glass-Weave Texture |
| | 42 Glass-Weave Exposure |